

HOSTAFORM® S 9243 XAP®2 LS HOSTAFORM®

POM copolymer, modified Injection molding type, elastomer-containing; with higher impact strength and slightly lower hardness, rigidity and chemical resistance than the basic type HOSTAFORM® C 9021 Reduced emission grade, Emission according to VDA 275 < 5 mg/kg good weld strength. Burning rate according to FMVSS 302 < 100 mm/min (1 mm thickness) Preliminary Datasheet for natural and colored grades

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Resin Identification Part Marking Code	POM >POM<		ISO 1043 ISO 11469
Rheological properties			
Melt volume-flow rate Temperature Load Moulding shrinkage range, parallel Moulding shrinkage range, normal	4 190 2.16 1.9 1.8	kg %	ISO 1133 ISO 294-4, 2577 ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus Tensile stress at yield, 50mm/min Tensile strain at yield, 50mm/min Nominal strain at break Flexural modulus Tensile creep modulus, 1h Tensile creep modulus, 1000h Charpy impact strength, 23°C Charpy impact strength, -30°C Charpy notched impact strength, 23°C Charpy notched impact strength, -30°C Poisson's ratio [P]: Partial Break [C]: Calculated	9 40 1850 1700 950 N 200 ^[P]	MPa % % MPa	ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 527-1/-2 ISO 178 ISO 899-1 ISO 899-1 ISO 179/1eU ISO 179/1eU ISO 179/1eA ISO 179/1eA
Thermal properties Melting temperature, 10°C/min Temperature of deflection under load, 1.8 MPa Coefficient of linear thermal expansion (CLTE), parallel Flammability Burning rate, Thickness 1 mm	120	°C °C E-6/K mm/min	ISO 11357-1/-3 ISO 75-1/-2 ISO 11359-1/-2 ISO 3795 (FMVSS 302)
Electrical properties Relative permittivity, 100Hz Relative permittivity, 1MHz Dissipation factor, 100Hz Dissipation factor, 1MHz Volume resistivity Surface resistivity	60	E-4 E-4 Ohm.m Ohm	IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-2-1 IEC 62631-3-1 IEC 62631-3-2

Printed: 2024-05-02 Page: 1 of 2

Revised: 2024-03-11 Source: Celanese Materials Database



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Comparative tracking index 600 IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2 %	Sim. to ISO 62
Water absorption, 2mm	1 %	Sim. to ISO 62
Density	1330 kg/m ³	ISO 1183

Injection

Drying Temperature	120	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.15	%
Screw tangential speed	≤0.202	m/s
Min. mould temperature	60	°C
Max. mould temperature	80	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Additives Release agent

Additional information

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

The product can then be stored in standard conditions until processed.

Printed: 2024-05-02 Page: 2 of 2

Revised: 2024-03-11 Source: Celanese Materials Database

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